	Туре	L #	Hits	Search Text	DBs
1	BRS	L1	8128	(ceramic) near15 (ion)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
2	BRS	L2	161	(ceramic) near15 (ion- conducting)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
3	BRS	<b>L</b> 3	32	(ceramic) near15 (ion- conducting) near15 (electrode)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
4	BRS	L4	0	(pattern\$3 near3 ceramic) near15 (ion-conducting) near15 (electrode)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Туре	L #	Hits	Search Text	DBs
5	BRS	<b>L</b> 5	32	(pattern\$3 near3 ceramic) near15 (ion)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
6	BRS	L6	202	(pattern\$3 near3 ceramic) near15 (oxides)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
7	BRS	L7	36	((pattern\$3 near3 ceramic) near (film or layer)) near15 (oxides)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
8	BRS	L8	50	(pattern\$3 near3 ceramic) near25 (precursor)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Туре	L #	Hits	Search Text	DBs
9	BRS	L9	5	(pattern\$3 near3 ceramic) near25 (precursor) near25 (photoresist)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
10	BRS	L10	0	(metal near salt) near25 (precursor) near25 (photoresist)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
11	BRS	L11	2	<pre>(metal near3 salt) near25 / (precursor) near25 (photoresist)</pre>	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
12	BRS	L12	8	(salt) near25 (precursor) near25 (photoresist)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Туре	L#	Hits	Search Text	DBs
13	BRS	L13	16410	(salt) near25 (precursor)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
14	BRS	L14	907	(salt) near25 (precursor) near25 (liquid)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
15	BRS	L15	176	(salt) near25 (precursor) near25 (liquid) near25 (dissolv\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
16	BRS	L16	7130	(salt) near25 (liquid) near25 (dissolv\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Туре	L #	Hits	Search Text	DBs
17	BRS	L17	112	(salt) near25 (liquid) near25 (dissolv\$3) near25 (substrate)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
18	BRS	L18	5	((salt) near25 (liquid) near25 (dissolv\$3) near25 (substrate)) near25 (pattern\$3 or etch\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
19	BRS	L19	73	((salt) near25 (dissolv\$3) near25 (substrate)) near25 (pattern\$3 or etch\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
20	BRS	L20	74	((salt) near25 (dissolv\$3) near25 (substrate or wafer)) near25 (pattern\$3 or etch\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Туре	L#	Hits	Search Text	DBs
21	BRS	L21	105357	(metal near15 pattern\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
22	BRS	L22	4	(metal-organic near3 precursor) near15 (pattern\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
23	BRS	L23	216	(solution near3 precursor) near15 (pattern\$3)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B
24	BRS	L24	4	(solution near3 precursor) near15 (pattern\$3) near25 (ceramic)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B

	Туре	L #	Hits	Search Text	DBs
25	BRS	L25	894	(solution or precursor) near15 (pattern\$3) near25	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B